



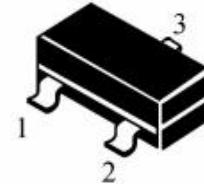
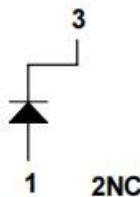
安徽富信半导体科技有限公司

ANHUI FOSAN SEMICONDUCTOR TECHNOLOGY CO., LTD.

BAS19

## SOT-23 Switching Diode 开关二极管

### ■ Internal Configuration 内部结构



### ■ Features 特点

Characteristic 特性参数	Symbol 符号	Max 最大值	Unit 单位
Power dissipation 耗散功率	PD(Ta=25°C)	250	mW
Forward Current 正向电流	I <sub>F</sub>	200	mA
Reverse Voltage 反向电压	V <sub>R</sub>	100	V
Junction and Storage Temperature 结温和储藏温度	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150°C	

### ■ Device Marking 产品打标

BAS19-JP

### ■ Electrical Characteristics 电特性

(TA=25°C unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Min 最小值	Max 最大值	Unit 单位
Reverse Breakdown Voltage 反向击穿电压 (IR=100uA)	V <sub>(BR)</sub>	100	—	V
Reverse Leakage Current(VR=50V) 反向漏电流(VR=100V)	IR	—	25 0.1	nA μA
Forward Voltage(I <sub>F</sub> =1mA) 正向电压(I <sub>F</sub> =10mA) (I <sub>F</sub> =50mA) (I <sub>F</sub> =150mA)	V <sub>F</sub>	—	0.715 0.855 1.0 1.25	V
Diode Capacitance 二极管电容 (VR=0V, f=1MHz)	C <sub>T</sub>	—	2	pF
Reverse Recovery Time 反向恢复时间	T <sub>rr</sub>	—	4	nS

## ■ Typical Characteristic Curve 典型特性曲线

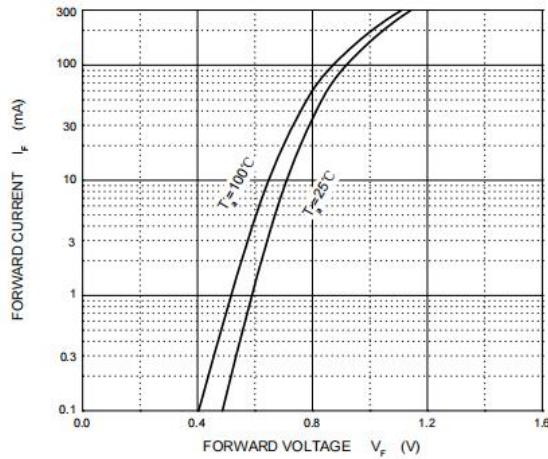


Figure 1: Forward Characteristics

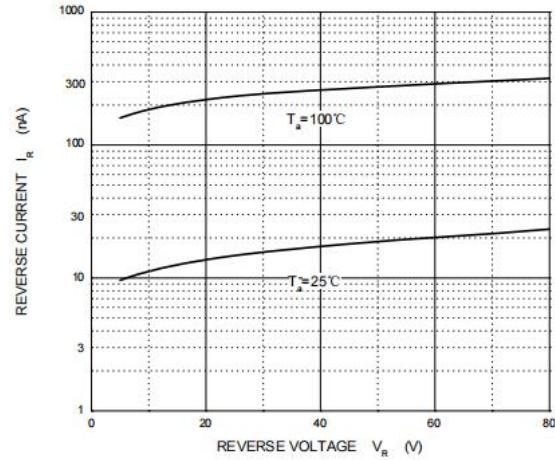


Figure 2: Leakage Current

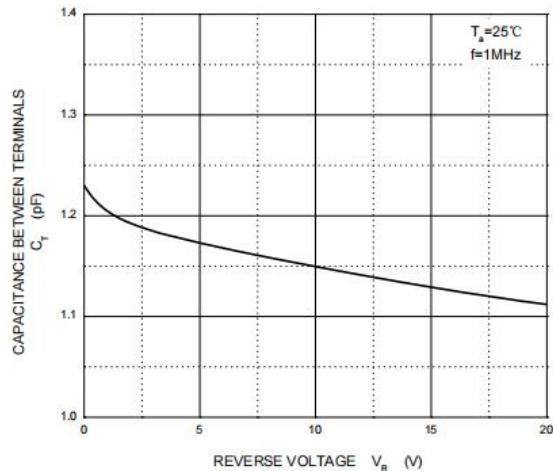


Figure 3: Capacitance Characteristics

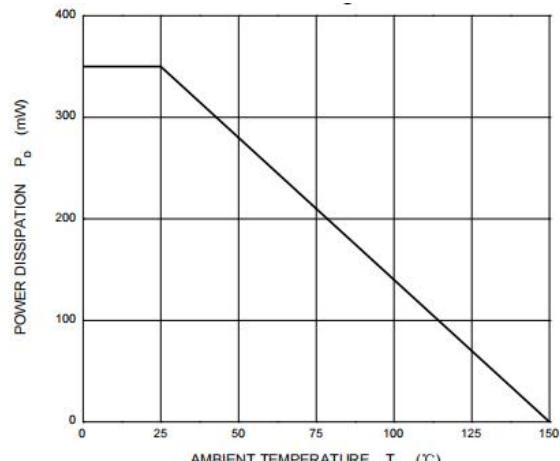
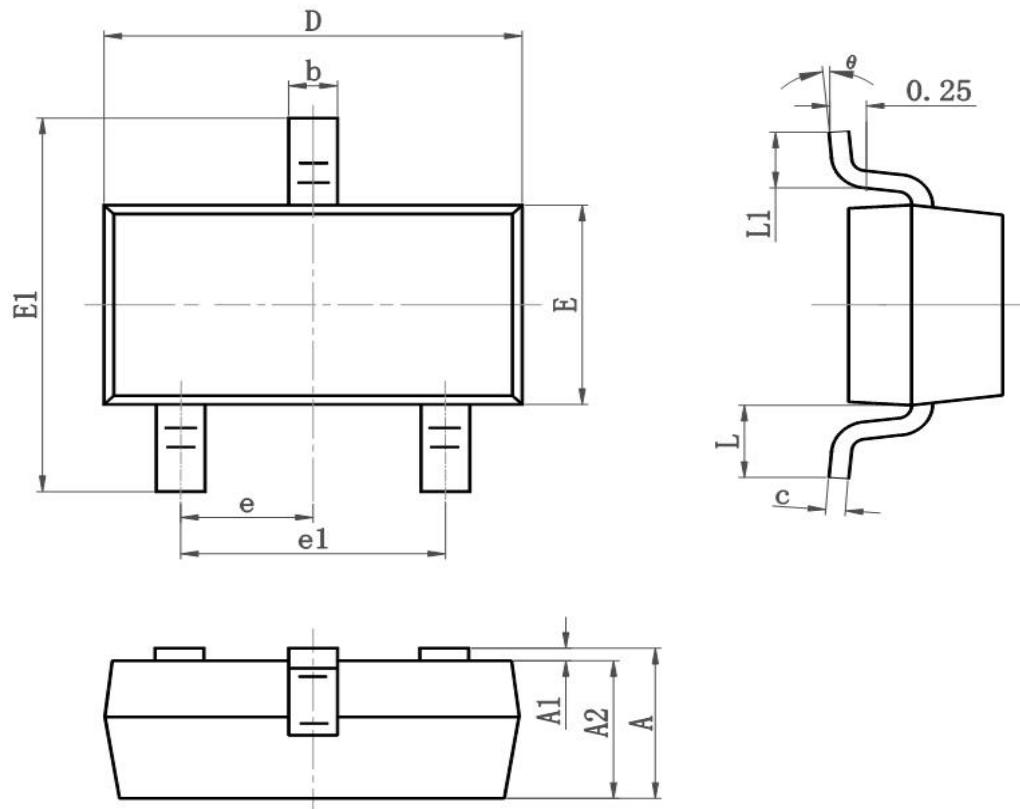


Figure 4: Power Derating Curve

## ■ Dimension 外形封装尺寸



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.050	0.055
E1	2.250	2.550	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°